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What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	ARM® Cortex®-M4
Core Size	32-Bit Single-Core
Speed	72MHz
Connectivity	CANbus, EBI/EMI, Ethernet, I ² C, IrDA, LINbus, MMC/SD/SDIO, QSPI, SmartCard, SPI, UART/USART, USB
Peripherals	Brown-out Detect/Reset, DMA, LCD, POR, PWM, WDT
Number of I/O	93
Program Memory Size	2MB (2M x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	512K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.8V
Data Converters	A/D 16x12b SAR; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	120-VFBGA
Supplier Device Package	120-BGA (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/silicon-labs/efm32gg11b820f2048gl120-b

4.1.10.6 USB High-Frequency RC Oscillator (USHFRCO)

Table 4.17. USB High-Frequency RC Oscillator (USHFRCO)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Frequency accuracy	$f_{USHFRCO_ACC}$	At production calibrated frequencies, across supply voltage and temperature	TBD	—	TBD	%
		USB clock recovery enabled, Active connection as device, FINE-TUNINGEN ¹ = 1	-0.25	—	0.25	%
Start-up time	$t_{USHFRCO}$		—	300	—	ns
Current consumption on all supplies	$I_{USHFRCO}$	$f_{USHFRCO} = 48$ MHz, FINETUNINGEN ¹ = 1	—	340	TBD	μ A
		$f_{USHFRCO} = 50$ MHz, FINETUNINGEN ¹ = 0	—	342	TBD	μ A
		$f_{USHFRCO} = 48$ MHz, FINETUNINGEN ¹ = 0	—	292	TBD	μ A
		$f_{USHFRCO} = 32$ MHz, FINETUNINGEN ¹ = 0	—	223	TBD	μ A
		$f_{USHFRCO} = 16$ MHz, FINETUNINGEN ¹ = 0	—	132	TBD	μ A
Period jitter	$PJ_{USHFRCO}$		—	0.2	—	% RMS
Note: 1. In the CMU_USHFRCOCTRL register.						

4.1.10.7 Ultra-low Frequency RC Oscillator (ULFRCO)

Table 4.18. Ultra-low Frequency RC Oscillator (ULFRCO)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Oscillation frequency	f_{ULFRCO}		TBD	1	TBD	kHz

4.1.16 Digital to Analog Converter (VDAC)

DRIVESTRENGTH = 2 unless otherwise specified. Primary VDAC output.

Table 4.24. Digital to Analog Converter (VDAC)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Output voltage	V_{DACOUT}	Single-Ended	0	—	V_{VREF}	V
		Differential ²	$-V_{VREF}$	—	V_{VREF}	V
Current consumption including references (2 channels) ¹	I_{DAC}	500 ksps, 12-bit, DRIVESTRENGTH = 2, REFSEL = 4	—	402	—	μA
		44.1 ksps, 12-bit, DRIVESTRENGTH = 1, REFSEL = 4	—	88	—	μA
		200 Hz refresh rate, 12-bit Sample-Off mode in EM2, DRIVESTRENGTH = 2, BGRREQTIME = 1, EM2REFENTIME = 9, REFSEL = 4, SETTLETIME = 0x0A, WARMUPTIME = 0x02	—	2	—	μA
Current from HFPERCLK ⁴	I_{DAC_CLK}		—	5.25	—	$\mu A/MHz$
Sample rate	SR_{DAC}		—	—	500	ksps
DAC clock frequency	f_{DAC}		—	—	1	MHz
Conversion time	$t_{DACCONV}$	$f_{DAC} = 1MHz$	2	—	—	μs
Settling time	$t_{DACSETTLE}$	50% fs step settling to 5 LSB	—	2.5	—	μs
Startup time	$t_{DACSTARTUP}$	Enable to 90% fs output, settling to 10 LSB	—	—	12	μs
Output impedance	R_{OUT}	DRIVESTRENGTH = 2, $0.4 V \leq V_{OUT} \leq V_{OPA} - 0.4 V$, $-8 mA < I_{OUT} < 8 mA$, Full supply range	—	2	—	Ω
		DRIVESTRENGTH = 0 or 1, $0.4 V \leq V_{OUT} \leq V_{OPA} - 0.4 V$, $-400 \mu A < I_{OUT} < 400 \mu A$, Full supply range	—	2	—	Ω
		DRIVESTRENGTH = 2, $0.1 V \leq V_{OUT} \leq V_{OPA} - 0.1 V$, $-2 mA < I_{OUT} < 2 mA$, Full supply range	—	2	—	Ω
		DRIVESTRENGTH = 0 or 1, $0.1 V \leq V_{OUT} \leq V_{OPA} - 0.1 V$, $-100 \mu A < I_{OUT} < 100 \mu A$, Full supply range	—	2	—	Ω
Power supply rejection ratio ⁶	PSRR	$V_{out} = 50\% fs, DC$	—	65.5	—	dB

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Slew rate ⁵	SR	DRIVESTRENGTH = 3, INCBW=1 ³	—	4.7	—	V/ μ s
		DRIVESTRENGTH = 3, INCBW=0	—	1.5	—	V/ μ s
		DRIVESTRENGTH = 2, INCBW=1 ³	—	1.27	—	V/ μ s
		DRIVESTRENGTH = 2, INCBW=0	—	0.42	—	V/ μ s
		DRIVESTRENGTH = 1, INCBW=1 ³	—	0.17	—	V/ μ s
		DRIVESTRENGTH = 1, INCBW=0	—	0.058	—	V/ μ s
		DRIVESTRENGTH = 0, INCBW=1 ³	—	0.044	—	V/ μ s
		DRIVESTRENGTH = 0, INCBW=0	—	0.015	—	V/ μ s
Startup time ⁶	T _{START}	DRIVESTRENGTH = 2	—	—	12	μ s
Input offset voltage	V _{OSI}	DRIVESTRENGTH = 2 or 3, T = 25 °C	TBD	—	TBD	mV
		DRIVESTRENGTH = 1 or 0, T = 25 °C	TBD	—	TBD	mV
		DRIVESTRENGTH = 2 or 3, across operating temperature range	TBD	—	TBD	mV
		DRIVESTRENGTH = 1 or 0, across operating temperature range	TBD	—	TBD	mV
DC power supply rejection ratio ⁹	PSRR _{DC}	Input referred	—	70	—	dB
DC common-mode rejection ratio ⁹	CMRR _{DC}	Input referred	—	70	—	dB
Total harmonic distortion	THD _{OPA}	DRIVESTRENGTH = 2, 3x Gain connection, 1 kHz, V _{OUT} = 0.1 V to V _{OPA} - 0.1 V	—	90	—	dB
		DRIVESTRENGTH = 0, 3x Gain connection, 0.1 kHz, V _{OUT} = 0.1 V to V _{OPA} - 0.1 V	—	90	—	dB

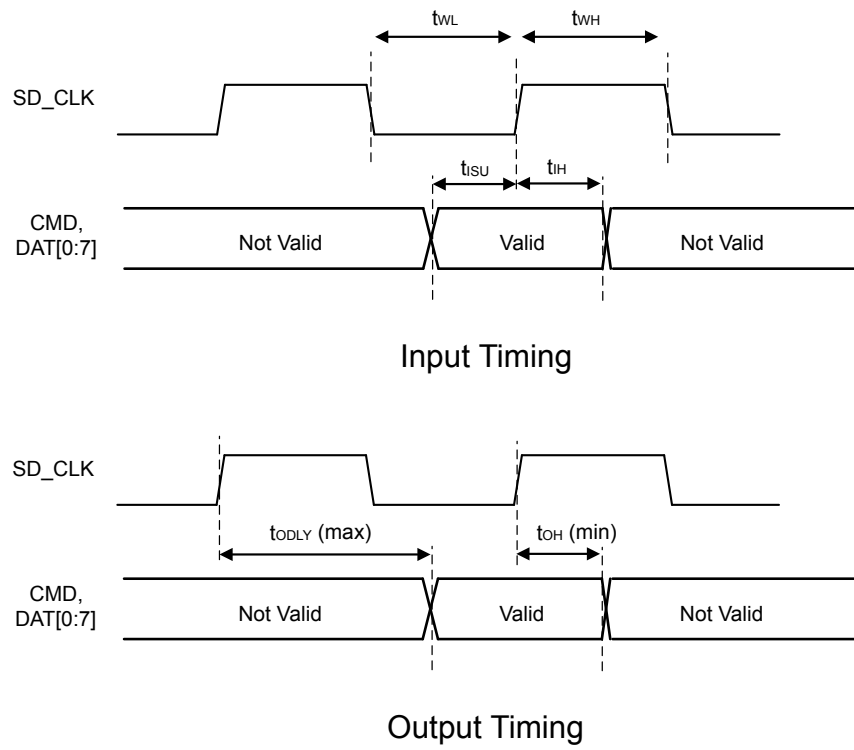


Figure 4.17. SDIO MMC SDR Mode Timing

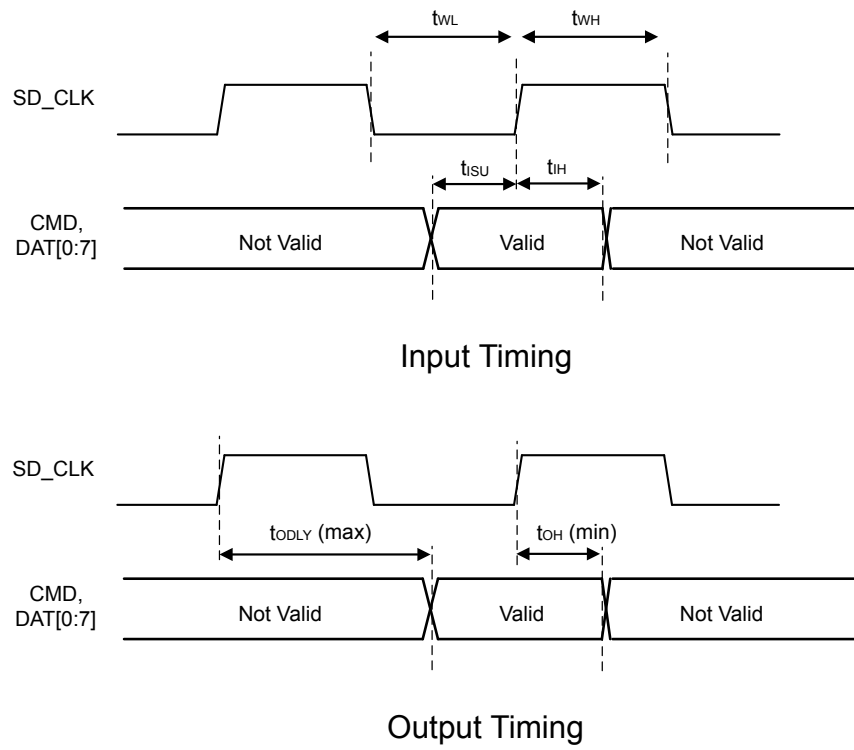


Figure 4.18. SDIO MMC SDR Mode Timing

4.1.28.2 QSPI DDR Mode

QSPI DDR Mode Timing (Location 0)

Timing is specified with voltage scaling disabled, PHY-mode, route location 0 only, TX DLL = 35, RX DLL = 70, 20-25 pF loading per GPIO, and slew rate for all GPIO set to 6, DRIVESTRENGTH = STRONG.

Table 4.56. QSPI DDR Mode Timing (Location 0)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Half SCLK period	T/2	HFXO	$(1/F_{SCLK})^*$ 0.4 - 0.4	—	—	ns
		HFRCO, AUXHFRCO, USHFRCO	$(1/F_{SCLK})^*$ 0.44	—	—	ns
Output valid	t _{OV}		—	—	T/2 - 5.0	ns
Output hold	t _{OH}		T/2 - 39.4	—	—	ns
Input setup	t _{SU}		33.1	—	—	ns
Input hold	t _H		-0.9	—	—	ns

Pin Name	Pin(s)	Description	Pin Name	Pin(s)	Description
<p>Note:</p> <ol style="list-style-type: none"> GPIO with 5V tolerance are indicated by (5V). The pins PD13, PD14, and PD15 will not be 5V tolerant on all future devices. In order to preserve upgrade options with full hardware compatibility, do not use these pins with 5V domains. 					

5.3 EFM32GG11B8xx in BGA120 Device Pinout

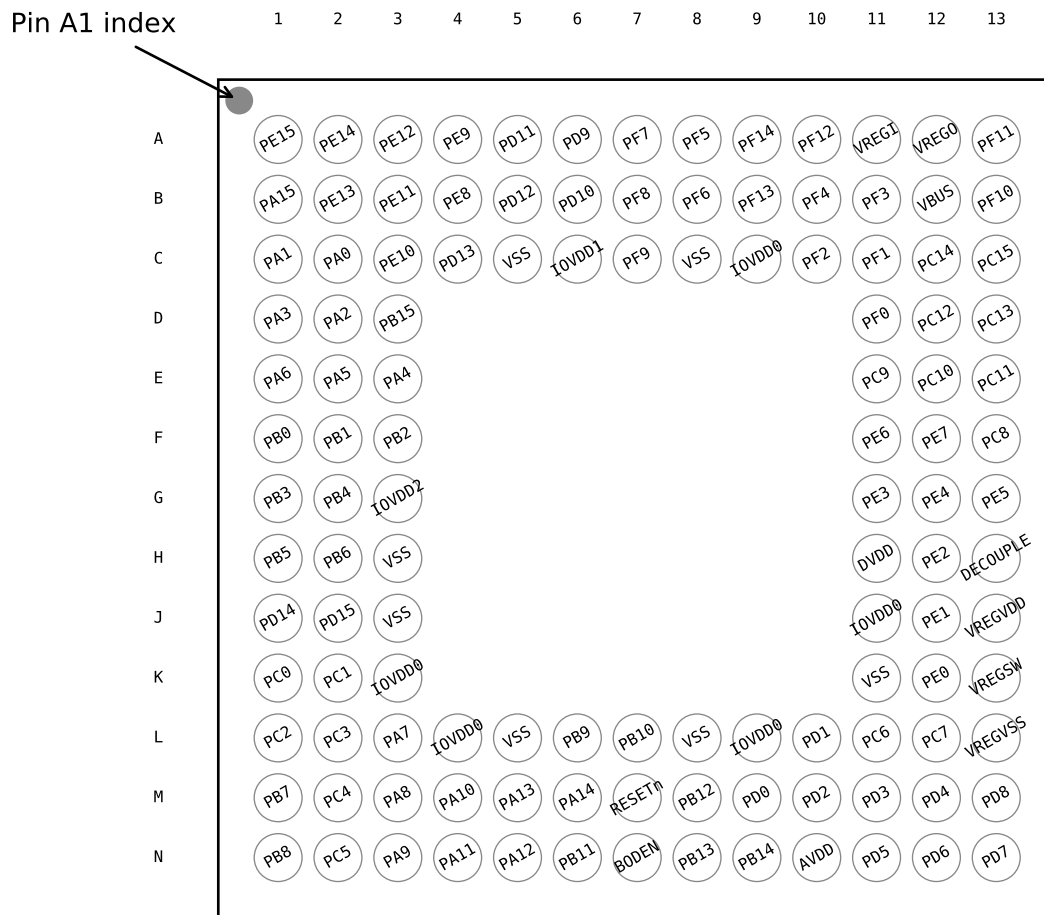


Figure 5.3. EFM32GG11B8xx in BGA120 Device Pinout

The following table provides package pin connections and general descriptions of pin functionality. For detailed information on the supported features for each GPIO pin, see [5.20 GPIO Functionality Table](#) or [5.21 Alternate Functionality Overview](#).

Table 5.3. EFM32GG11B8xx in BGA120 Device Pinout

Pin Name	Pin(s)	Description	Pin Name	Pin(s)	Description
PE15	A1	GPIO	PE14	A2	GPIO
PE12	A3	GPIO	PE9	A4	GPIO
PD11	A5	GPIO	PD9	A6	GPIO
PF7	A7	GPIO	PF5	A8	GPIO
PF14	A9	GPIO (5V)	PF12	A10	GPIO
VREGI	A11	Input to 5 V regulator.	VREGO	A12	Decoupling for 5 V regulator and regulator output. Power for USB PHY in USB-enabled OPNs

5.4 EFM32GG11B5xx in BGA120 Device Pinout

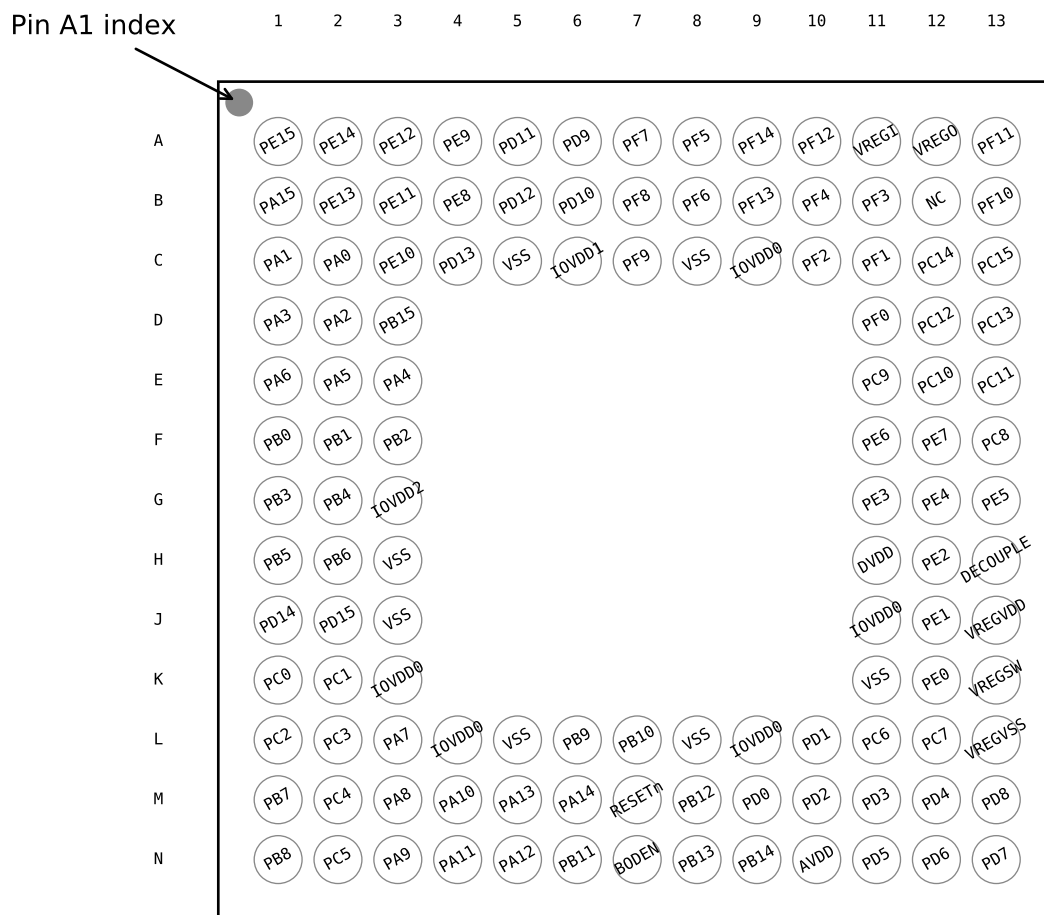


Figure 5.4. EFM32GG11B5xx in BGA120 Device Pinout

The following table provides package pin connections and general descriptions of pin functionality. For detailed information on the supported features for each GPIO pin, see [5.20 GPIO Functionality Table](#) or [5.21 Alternate Functionality Overview](#).

Table 5.4. EFM32GG11B5xx in BGA120 Device Pinout

Pin Name	Pin(s)	Description	Pin Name	Pin(s)	Description
PE15	A1	GPIO	PE14	A2	GPIO
PE12	A3	GPIO	PE9	A4	GPIO
PD11	A5	GPIO	PD9	A6	GPIO
PF7	A7	GPIO	PF5	A8	GPIO
PF14	A9	GPIO (5V)	PF12	A10	GPIO
VREGI	A11	Input to 5 V regulator.	VREGO	A12	Decoupling for 5 V regulator and regulator output. Power for USB PHY in USB-enabled OPNs

Pin Name	Pin(s)	Description	Pin Name	Pin(s)	Description
PC1	J1	GPIO (5V)	PC3	J2	GPIO (5V)
PD15	J3	GPIO (5V)	PA12	J4	GPIO (5V)
PA9	J5	GPIO	PA10	J6	GPIO
PB9	J7	GPIO (5V)	PB10	J8	GPIO (5V)
PD2	J9	GPIO (5V)	PD3	J10	GPIO
PD4	J11	GPIO	PB7	K1	GPIO
PC4	K2	GPIO	PA13	K3	GPIO (5V)
PA11	K5	GPIO	RESETn	K6	Reset input, active low. To apply an external reset source to this pin, it is required to only drive this pin low during reset, and let the internal pull-up ensure that reset is released.
AVDD	K8 K9 L10	Analog power supply.	PD1	K11	GPIO
PB8	L1	GPIO	PC5	L2	GPIO
PA14	L3	GPIO	PB11	L5	GPIO
PB12	L6	GPIO	PB13	L8	GPIO
PB14	L9	GPIO	PD0	L11	GPIO (5V)

Note:

1. GPIO with 5V tolerance are indicated by (5V).
2. The pins PD13, PD14, and PD15 will not be 5V tolerant on all future devices. In order to preserve upgrade options with full hardware compatibility, do not use these pins with 5V domains.

Pin Name	Pin(s)	Description	Pin Name	Pin(s)	Description
PF2	78	GPIO	VBUS	79	USB VBUS signal and auxiliary input to 5 V regulator.
PF12	80	GPIO	PF5	81	GPIO
PF6	84	GPIO	PF7	85	GPIO
PF8	86	GPIO	PF9	87	GPIO
PD9	88	GPIO	PD10	89	GPIO
PD11	90	GPIO	PD12	91	GPIO
PE8	92	GPIO	PE9	93	GPIO
PE10	94	GPIO	PE11	95	GPIO
PE12	96	GPIO	PE13	97	GPIO
PE14	98	GPIO	PE15	99	GPIO
PA15	100	GPIO			

Note:

- GPIO with 5V tolerance are indicated by (5V).

5.12 EFM32GG11B8xx in QFP64 Device Pinout

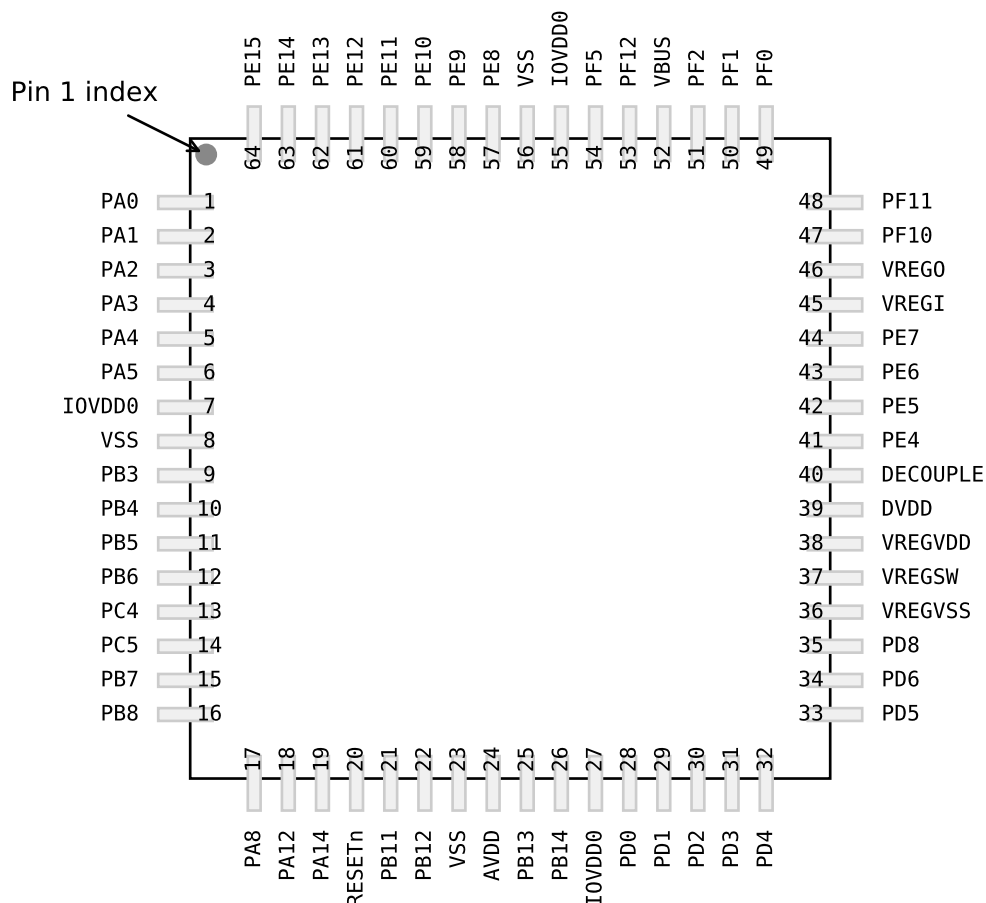


Figure 5.12. EFM32GG11B8xx in QFP64 Device Pinout

The following table provides package pin connections and general descriptions of pin functionality. For detailed information on the supported features for each GPIO pin, see [5.20 GPIO Functionality Table](#) or [5.21 Alternate Functionality Overview](#).

Table 5.12. EFM32GG11B8xx in QFP64 Device Pinout

Pin Name	Pin(s)	Description	Pin Name	Pin(s)	Description
PA0	1	GPIO	PA1	2	GPIO
PA2	3	GPIO	PA3	4	GPIO
PA4	5	GPIO	PA5	6	GPIO
IOVDD0	7 27 55	Digital IO power supply 0.	VSS	8 23 56	Ground
PB3	9	GPIO	PB4	10	GPIO
PB5	11	GPIO	PB6	12	GPIO

5.14 EFM32GG11B4xx in QFP64 Device Pinout

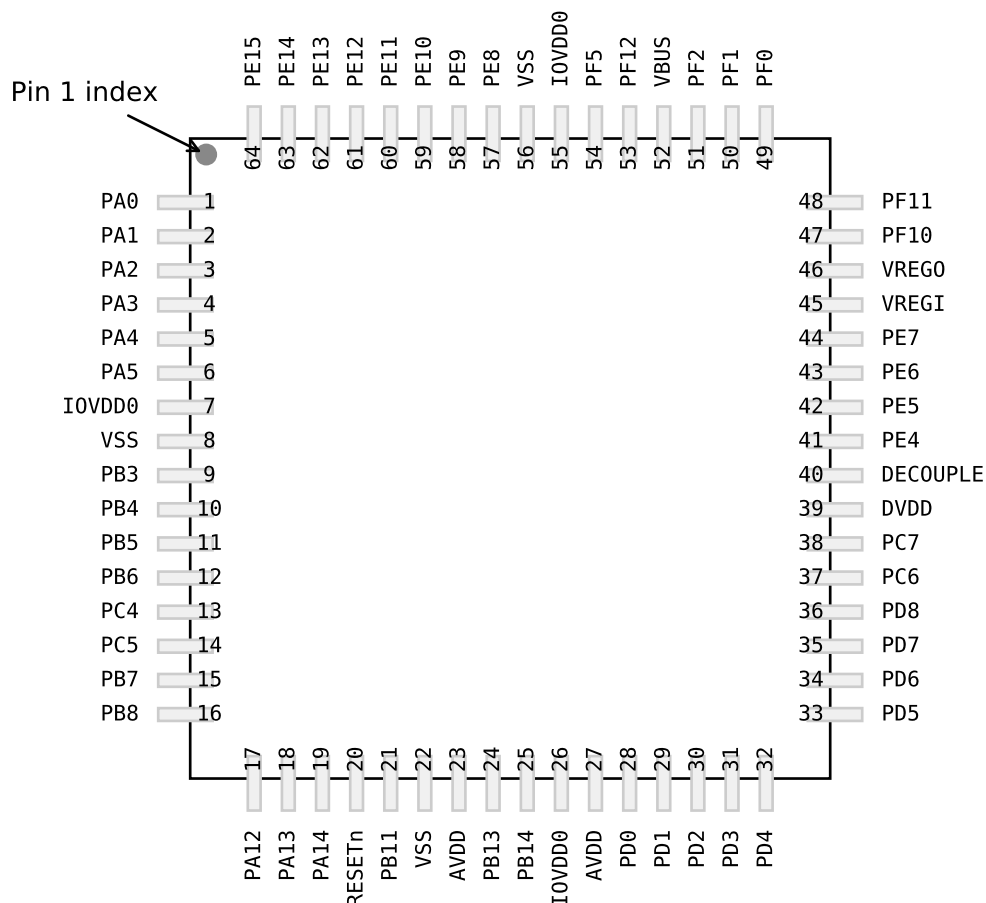


Figure 5.14. EFM32GG11B4xx in QFP64 Device Pinout

The following table provides package pin connections and general descriptions of pin functionality. For detailed information on the supported features for each GPIO pin, see [5.20 GPIO Functionality Table](#) or [5.21 Alternate Functionality Overview](#).

Table 5.14. EFM32GG11B4xx in QFP64 Device Pinout

Pin Name	Pin(s)	Description	Pin Name	Pin(s)	Description
PA0	1	GPIO	PA1	2	GPIO
PA2	3	GPIO	PA3	4	GPIO
PA4	5	GPIO	PA5	6	GPIO
IOVDD0	7 26 55	Digital IO power supply 0.	VSS	8 22 56	Ground
PB3	9	GPIO	PB4	10	GPIO
PB5	11	GPIO	PB6	12	GPIO

Pin Name	Pin(s)	Description	Pin Name	Pin(s)	Description
PC3	12	GPIO (5V)	PC4	13	GPIO
PC5	14	GPIO	PB7	15	GPIO
PB8	16	GPIO	PA8	17	GPIO
PA9	18	GPIO	PA10	19	GPIO
RESETn	20	Reset input, active low. To apply an external reset source to this pin, it is required to only drive this pin low during reset, and let the internal pull-up ensure that reset is released.	PB11	21	GPIO
PB12	22	GPIO	AVDD	23 27	Analog power supply.
PB13	24	GPIO	PB14	25	GPIO
PD0	28	GPIO (5V)	PD1	29	GPIO
PD2	30	GPIO (5V)	PD3	31	GPIO
PD4	32	GPIO	PD5	33	GPIO
PD6	34	GPIO	PD7	35	GPIO
PD8	36	GPIO	PC6	37	GPIO
PC7	38	GPIO	DVDD	39	Digital power supply.
DECOUPLE	40	Decouple output for on-chip voltage regulator. An external decoupling capacitor is required at this pin.	PC8	41	GPIO (5V)
PC9	42	GPIO (5V)	PC10	43	GPIO (5V)
PC11	44	GPIO (5V)	PC12	45	GPIO (5V)
PC13	46	GPIO (5V)	PC14	47	GPIO (5V)
PC15	48	GPIO (5V)	PF0	49	GPIO (5V)
PF1	50	GPIO (5V)	PF2	51	GPIO
PF3	52	GPIO	PF4	53	GPIO
PF5	54	GPIO	PE8	56	GPIO
PE9	57	GPIO	PE10	58	GPIO
PE11	59	GPIO	PE12	60	GPIO
PE13	61	GPIO	PE14	62	GPIO
PE15	63	GPIO	PA15	64	GPIO

Note:

1. GPIO with 5V tolerance are indicated by (5V).

GPIO Name	Pin Alternate Functionality / Description				
	Analog	EBI	Timers	Communication	Other
PD13		EBI_ARDY #1	TIM2_CDTI0 #1 TIM3_CC1 #6 WTIM0_CC1 #1	ETH_MDIO #1 US4_CTS #1 US5_CLK #1	ETM_TD1 #1
PI15				CAN1_TX #7 US3_CS #5	
PI14				CAN1_RX #7 US3_CLK #5	
PI13				CAN0_TX #7 US3_RX #5	
PI12				CAN0_RX #7 US3_TX #5	
PI10		EBI_A15 #2	TIM4_CC2 #3	US4_CTS #3	
PI7		EBI_A12 #2	TIM1_CC1 #7 TIM4_CC2 #2 WTIM3_CC1 #5	US4_RX #3	
PF15	BUSCY BUSDX		TIM1_CC2 #6 TIM4_CC2 #1 WTIM3_CC2 #7	US5_TX #2 I2C2_SDA #5	
PF12	BUSDY BUSCX	EBI_NANDREn #5	TIM4_CC2 #0 TIM1_CC3 #5 TIM5_CC0 #7 WTIM3_CC2 #6	US5_CS #2 I2C2_SCL #3 USB_ID	
PF4	BUSDY BUSCX LCD_SEG2	EBI_WEn #0 EBI_WEn #5	TIM4_CC1 #0 TIM0_CDTI1 #2 TIM1_CC2 #5 WTIM3_CC1 #6	US1_RTS #2 I2C2_SDA #3	PRS_CH1 #1
PC15	VDAC0_OUT1ALT / OPA1_OUTALT #3 BUSACMP1Y BU- SACMP1X	EBI_NANDREn #4	TIM0_CDTI2 #1 TIM1_CC2 #0 WTIM0_CC0 #4 LE- TIM0_OUT1 #5	US0_CLK #3 US1_CLK #3 US3_RTS #3 U0_RX #3 U1_RTS #0 LEU0_RX #5 I2C2_SCL #1	LES_CH15 PRS_CH1 #2 ACMP3_O #1 DBG_SWO #1
PC14	VDAC0_OUT1ALT / OPA1_OUTALT #2 BUSACMP1Y BU- SACMP1X	EBI_NANDWEn #4	TIM0_CDTI1 #1 TIM1_CC1 #0 TIM1_CC3 #4 TIM5_CC0 #6 WTIM3_CC0 #3 LE- TIM0_OUT0 #5 PCNT0_S1IN #0	US0_CS #3 US1_CS #3 US2_RTS #3 US3_CS #2 U0_TX #3 U1_CTS #0 LEU0_TX #5 I2C2_SDA #1	LES_CH14 PRS_CH0 #2 ACMP3_O #2
PA2	BUSBY BUSAX LCD_SEG15	EBI_AD11 #0 EBI_DTEN #3	TIM0_CC2 #0 TIM3_CC2 #4	ETH_RMIIIRD0 #0 ETH_MIIITXD2 #0 SDIO_DAT2 #1 US1_RX #6 US3_CLK #0 QSPI0_DQ0 #1	CMU_CLK0 #0 PRS_CH8 #1 ETM_TD0 #3
PG0	BUSACMP2Y BU- SACMP2X	EBI_AD00 #2	TIM6_CC0 #0 TIM2_CDTI0 #3 WTIM0_CDTI1 #1 LETIM1_OUT0 #6	ETH_MIIITXCLK #1 US3_TX #4 QSPI0_SCLK #2	CMU_CLK2 #3

GPIO Name	Pin Alternate Functionality / Description				
	Analog	EBI	Timers	Communication	Other
PD4	BUSADC0Y BU-SADC0X OPA2_P	EBI_A08 #1 EBI_A17 #3	TIM6_CC0 #7 WTIM0_CDTI0 #4 WTIM1_CC2 #1 WTIM2_CC1 #5	CAN1_TX #2 US1_CTS #1 US3_CLK #2 LEU0_TX #0 I2C1_SDA #3	CMU_CLKI0 #0 PRS_CH10 #2 ETM_TD2 #0 ETM_TD2 #2
PC0	VDAC0_OUT0ALT / OPA0_OUTALT #0 BUSACMP0Y BU-SACMP0X	EBI_AD07 #1 EBI_CS0 #2 EBI_REn #3 EBI_A23 #0	TIM0_CC1 #3 TIM2_CC1 #4 PCNT0_S0IN #2	ETH_MDIO #2 CAN0_RX #0 US0_TX #5 US1_TX #0 US1_CS #4 US2_RTS #0 US3_CS #3 I2C0_SDA #4	LES_CH0 PRS_CH2 #0
PC1	VDAC0_OUT0ALT / OPA0_OUTALT #1 BUSACMP0Y BU-SACMP0X	EBI_AD08 #1 EBI_CS1 #2 EBI_BL0 #3 EBI_A24 #0	TIM0_CC2 #3 TIM2_CC2 #4 WTIM0_CC0 #7 PCNT0_S1IN #2	ETH_MDC #2 CAN0_TX #0 US0_RX #5 US1_TX #4 US1_RX #0 US2_CTS #0 US3_RTS #1 I2C0_SCL #4	LES_CH1 PRS_CH3 #0
PC2	VDAC0_OUT0ALT / OPA0_OUTALT #2 BUSACMP0Y BU-SACMP0X	EBI_AD09 #1 EBI_CS2 #2 EBI_NANDWEEn #3 EBI_A25 #0	TIM0_CDTI0 #3 TIM2_CC0 #5 WTIM0_CC1 #7 LE-TIM1_OUT0 #3	ETH_TSUEXTCLK #2 CAN1_RX #0 US1_RX #4 US2_TX #0	LES_CH2 PRS_CH10 #1
PA8	BUSBY BUSAX LCD_SEG36	EBI_AD14 #1 EBI_A02 #3 EBI_DCLK #0	TIM2_CC0 #0 TIM0_CC0 #6 LE-TIM0_OUT0 #6 PCNT1_S1IN #4	US2_RX #2 US4_RTS #0	PRS_CH8 #0
PA11	BUSAY BUSBX LCD_SEG39	EBI_CS1 #1 EBI_A05 #3 EBI_HSNc #0	WTIM2_CC2 #0 LE-TIM1_OUT0 #1	US2_CTS #2	PRS_CH11 #0
PA13	BUSAY BUSBX	EBI_WEn #1 EBI_NANDWEEn #2 EBI_A01 #0 EBI_A07 #3	TIM0_CC2 #7 TIM2_CC1 #1 WTIM0_CDTI1 #2 WTIM2_CC1 #1 LE-TIM1_OUT1 #1 PCNT1_S1IN #5	CAN1_TX #5 US0_CS #5 US2_TX #3	PRS_CH13 #0
PB9	BUSAY BUSBX	EBI_ALE #1 EBI_NANDREn #2 EBI_A00 #1 EBI_A03 #0 EBI_A09 #3	WTIM2_CC0 #2 LE-TIM0_OUT0 #7	SDIO_WP #3 CAN0_RX #3 US1_CTS #0 U1_TX #2	PRS_CH13 #1 ACMP1_O #5
PB12	BUSBY BUSAX VDAC0_OUT1 / OPA1_OUT	EBI_A03 #1 EBI_A12 #3 EBI_CSTFT #2	TIM1_CC3 #3 WTIM2_CC0 #3 LE-TIM0_OUT1 #1 PCNT0_S0IN #7 PCNT1_S1IN #6	US2_CTS #1 US5_RTS #0 U1_RTS #2 I2C1_SCL #1	PRS_CH16 #1
PH2	BUSADC1Y BU-SADC1X	EBI_VSNc #2	TIM6_CC0 #3	US1_CTS #6	
PH5	BUSADC1Y BU-SADC1X	EBI_A17 #2	TIM6_CDTI0 #3 WTIM2_CC1 #6	US4_RX #4	
PH8	BUSACMP3Y BU-SACMP3X	EBI_A20 #2	TIM6_CC0 #4 WTIM1_CC0 #6 WTIM2_CC1 #7	US4_CTS #4	

Alternate	LOCATION		Description
	0 - 3	4 - 7	
ETH_MDIO	0: PB3 1: PD13 2: PC0 3: PA15		Ethernet Management Data I/O.
ETH_MIICOL	0: PB2 1: PG15 2: PB4		Ethernet MII Collision Detect.
ETH_MIICRS	0: PB1 1: PG14 2: PB3		Ethernet MII Carrier Sense.
ETH_MIIRXCLK	0: PA15 1: PG7 2: PD12		Ethernet MII Receive Clock.
ETH_MIIRXD0	0: PE12 1: PG11 2: PF9		Ethernet MII Receive Data Bit 0.
ETH_MIIRXD1	0: PE13 1: PG10 2: PD9		Ethernet MII Receive Data Bit 1.
ETH_MIIRXD2	0: PE14 1: PG9 2: PD10		Ethernet MII Receive Data Bit 2.
ETH_MIIRXD3	0: PE15 1: PG8 2: PD11		Ethernet MII Receive Data Bit 3.
ETH_MIIRXDV	0: PE11 1: PG12 2: PF8		Ethernet MII Receive Data Valid.
ETH_MIIRXER	0: PE10 1: PG13 2: PF7		Ethernet MII Receive Error.
ETH_MIITXCLK	0: PA0 1: PG0		Ethernet MII Transmit Clock.
ETH_MIITXD0	0: PA4 1: PG4		Ethernet MII Transmit Data Bit 0.
ETH_MIITXD1	0: PA3 1: PG3		Ethernet MII Transmit Data Bit 1.

Alternate	LOCATION		Description
	0 - 3	4 - 7	
PRS_CH20	0: PB4 1: PC12 2: PE2		Peripheral Reflex System PRS, channel 20.
PRS_CH21	0: PB5 1: PC13 2: PB11		Peripheral Reflex System PRS, channel 21.
PRS_CH22	0: PB7 1: PE0 2: PF6		Peripheral Reflex System PRS, channel 22.
PRS_CH23	0: PB8 1: PE1 2: PF7		Peripheral Reflex System PRS, channel 23.
QSPI0_CS0	0: PF7 1: PA0 2: PG9		Quad SPI 0 Chip Select 0.
QSPI0_CS1	0: PF8 1: PA1 2: PG10		Quad SPI 0 Chip Select 1.
QSPI0_DQ0	0: PD9 1: PA2 2: PG1		Quad SPI 0 Data 0.
QSPI0_DQ1	0: PD10 1: PA3 2: PG2		Quad SPI 0 Data 1.
QSPI0_DQ2	0: PD11 1: PA4 2: PG3		Quad SPI 0 Data 2.
QSPI0_DQ3	0: PD12 1: PA5 2: PG4		Quad SPI 0 Data 3.
QSPI0_DQ4	0: PE8 1: PB3 2: PG5		Quad SPI 0 Data 4.
QSPI0_DQ5	0: PE9 1: PB4 2: PG6		Quad SPI 0 Data 5.
QSPI0_DQ6	0: PE10 1: PB5 2: PG7		Quad SPI 0 Data 6.

Table 7.1. BGA152 Package Dimensions

Dimension	Min	Typ	Max
A	0.78	0.84	0.90
A1	0.13	0.18	0.23
A3	0.16	0.20	0.24
A2	0.45 REF		
D	8.00 BSC		
e	0.50 BSC		
E	8.00 BSC		
D1	6.50 BSC		
E1	6.50 BSC		
b	0.20	0.25	0.30
aaa	0.10		
bbb	0.10		
ddd	0.08		
eee	0.15		
fff	0.05		

Note:

1. All dimensions shown are in millimeters (mm) unless otherwise noted.
2. Dimensioning and Tolerancing per ANSI Y14.5M-1994.
3. Recommended card reflow profile is per the JEDEC/IPC J-STD-020 specification for Small Body Components.

Table 10.2. TQFP100 PCB Land Pattern Dimensions

Dimension	Min	Nom	Max
C1		15.4	
C2		15.4	
E		0.50 BSC	
X		0.30	
Y		1.50	

Note:

1. All dimensions shown are in millimeters (mm) unless otherwise noted.
2. This Land Pattern Design is based on the IPC-7351 guidelines.
3. All metal pads are to be non-solder mask defined (NSMD). Clearance between the solder mask and the metal pad is to be 60 µm minimum, all the way around the pad.
4. A stainless steel, laser-cut and electro-polished stencil with trapezoidal walls should be used to assure good solder paste release.
5. The stencil thickness should be 0.125 mm (5 mils).
6. The ratio of stencil aperture to land pad size should be 1:1 for all perimeter pads.
7. A No-Clean, Type-3 solder paste is recommended.
8. The recommended card reflow profile is per the JEDEC/IPC J-STD-020C specification for Small Body Components.

10.3 TQFP100 Package Marking



Figure 10.3. TQFP100 Package Marking

The package marking consists of:

- P P P P P P P P P P – The part number designation.
- T T T T T T – A trace or manufacturing code. The first letter is the device revision.
- Y Y – The last 2 digits of the assembly year.
- W W – The 2-digit workweek when the device was assembled.